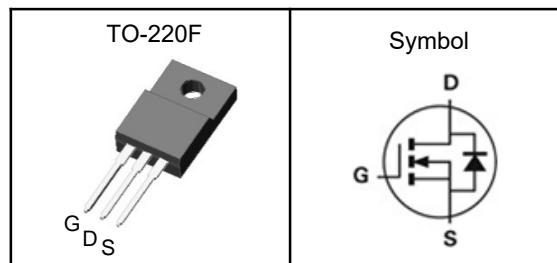


650V Super Junction Power MOSFET

Features

- Low drain-source on-resistance: $R_{DS(ON)}=0.078\Omega$ (typ)
- Easy to control gate switching
- Enhancement mode: $V_{th} = 2.5$ to $4.5V$
- 100% avalanche tested
- RoHS compliant

Pin Description



Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger, Lighting.

| | | |
|------------------|-----|-----------|
| V_{DSS} | 650 | V |
| $R_{DS(ON)-Typ}$ | 78 | $m\Omega$ |
| I_D | 32 | A |

Absolute Maximum Ratings ($T_J=25^\circ C$, Unless Otherwise Noted)

| Symbol | Parameter | Rating | Unit |
|--------------|--|------------------|------------|
| V_{DSS} | Drain-Source Voltage | 650 | V |
| V_{GSS} | Gate-Source Voltage | ± 30 | V |
| T_J | Maximum Junction Temperature | -55 to 150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| E_{AS} | Single Pulse Avalanche Energy ^③ | 199 | mJ |
| $I_{DM}^{①}$ | 300 μ s Pulse Drain Current Tested | 96 | A |
| I_D | Continuous Drain Current | $T_c=25^\circ C$ | 32 |
| P_D | Maximum Power Dissipation | $T_c=25^\circ C$ | 43 |
| | | | W |

Thermal Characteristics

| Symbol | Parameter | Rating | Unit |
|-----------------|--|--------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ₁ (Max) | 62 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ₁ | 2.9 | $^\circ C/W$ |

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature $150^\circ C$.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

650V Super Junction Power MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|---|----------------------------------|---|-----|------|-----------|------------------|
| Static Electrical Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$ | 650 | --- | --- | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $\text{V}_{\text{DS}}=600\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$ | --- | --- | 1 | μA |
| $\text{V}_{\text{GS(th)}}$ | Gate Threshold Voltage | $\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D=1.7\text{mA}$ | 2.5 | --- | 4.5 | V |
| I_{GSS} | Gate Leakage Current | $\text{V}_{\text{GS}}=\pm 30\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| $\text{R}_{\text{DS(ON)}}$ | Drain-Source On-state Resistance | $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=15.3\text{A}$ | --- | 78 | 90 | $\text{m}\Omega$ |
| Dynamic Characteristics^⑤ | | | | | | |
| C_{iss} | Input Capacitance | $\text{V}_{\text{GS}}=0\text{V}$, $\text{V}_{\text{DS}}=400\text{V}$, Freq.=1MHz | --- | 2270 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 58 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 9 | --- | |
| $\text{T}_{\text{d(on)}}$ | Turn-on Delay Time | $\text{V}_{\text{DD}}=400\text{V}$, $\text{R}_G=10\Omega$, $\text{I}_D=15.3\text{A}$ | --- | 17 | --- | nS |
| T_r | Turn-on Rise Time | | --- | 10 | --- | |
| $\text{T}_{\text{d(off)}}$ | Turn-off Delay Time | | --- | 86 | --- | |
| T_f | Turn-off Fall Time | | --- | 11 | --- | |
| Q_g | Total Gate Charge | $\text{V}_{\text{DS}}=400\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=10\text{A}$ | --- | 52 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 12.7 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 22.4 | --- | |
| Source-Drain Characteristics ($T_J=25^\circ\text{C}$) | | | | | | |
| $\text{V}_{\text{SD}}^{④}$ | Diode Forward Voltage | $\text{I}_F=15.3\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$ | --- | --- | 1.2 | V |
| t_{rr} | Reverse Recovery Time | $\text{V}_R=400\text{V}$, $\text{I}_F=15.3\text{A}$, $d\text{i}/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$ | --- | 346 | --- | nS |
| Q_{rr} | Reverse Recovery Charge | | --- | 5.1 | --- | nC |

Note ④ : Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

650V Super Junction Power MOSFET

Hnd]WU 7\ UFUWYf]ghWg

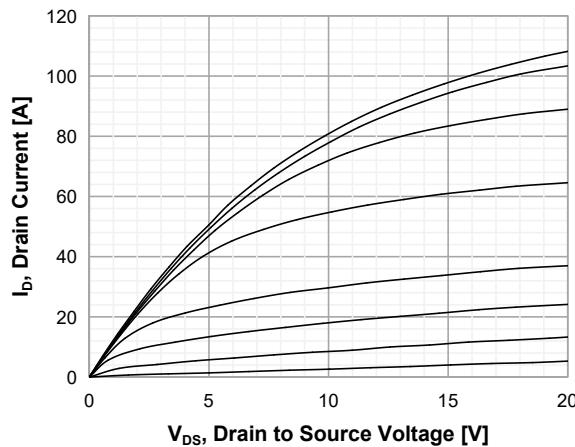


Figure 1. On-Region Characteristics

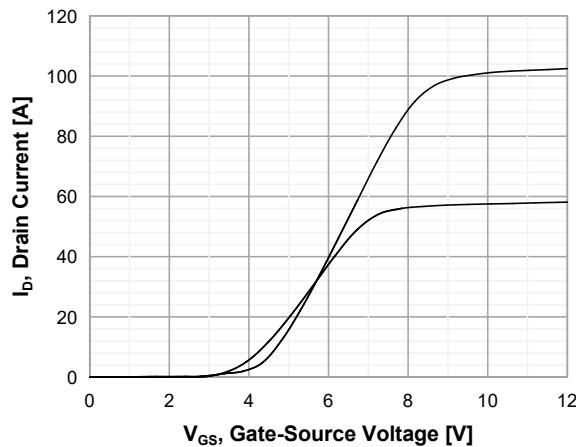


Figure 2. Transfer Characteristics

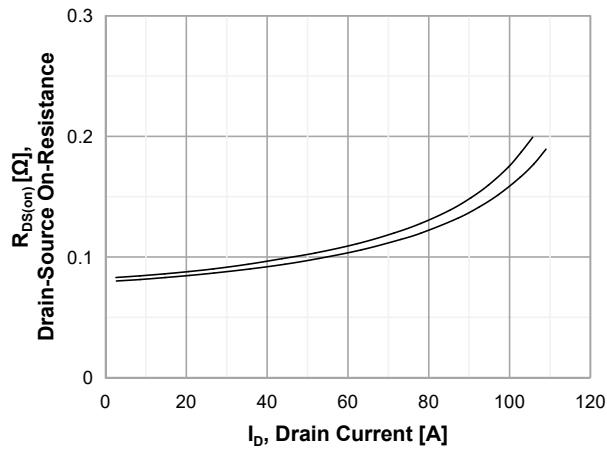


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

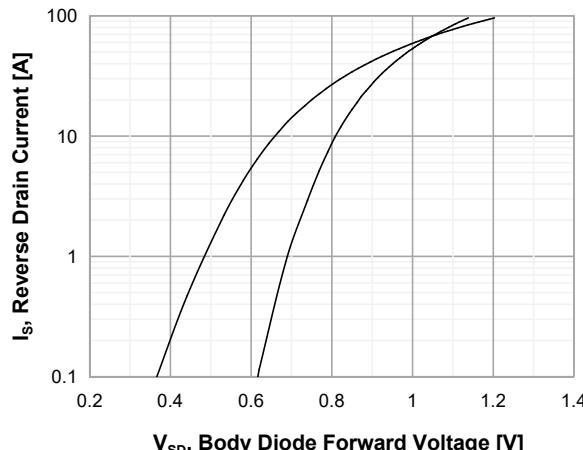


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

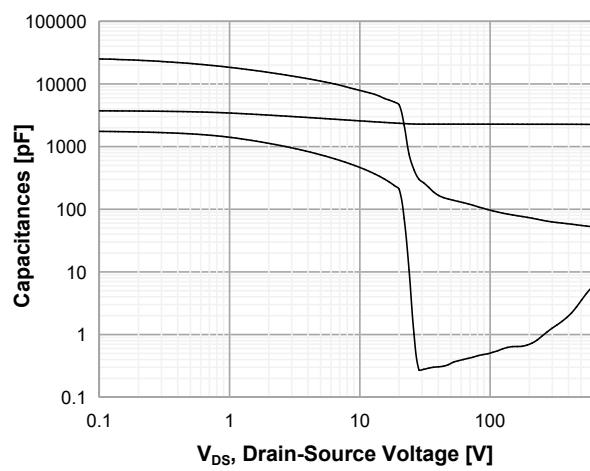


Figure 5. Capacitance Characteristics

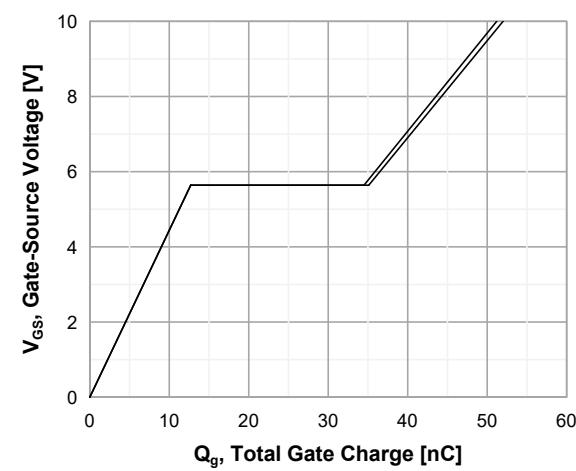
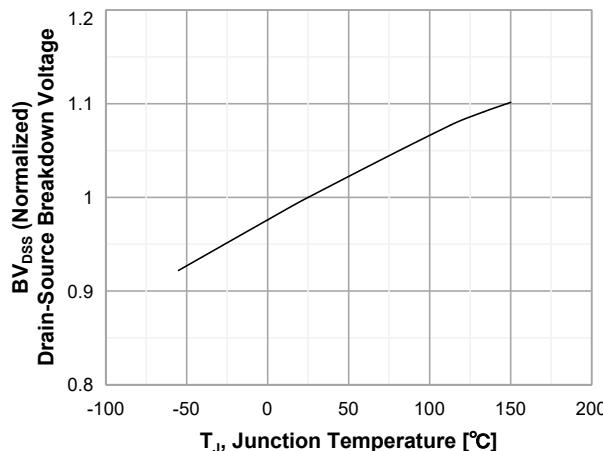
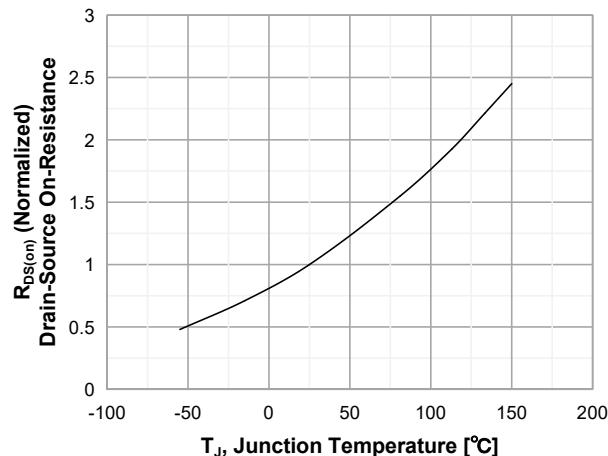


Figure 6. Gate Charge Characteristics

650V Super Junction Power MOSFET



**Figure 7. Breakdown Voltage Variation
vs Temperature**



**Figure 8. On-Resistance Variation
vs Temperature**

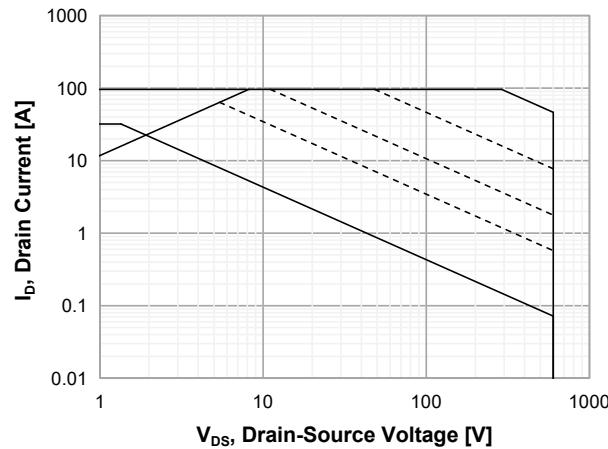
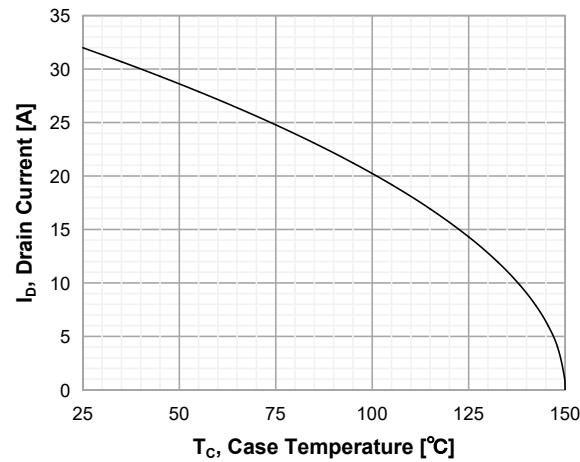


Figure 9. Maximum Safe Operating Area



**Figure 10. Maximum Drain Current vs.
Case Temperature**

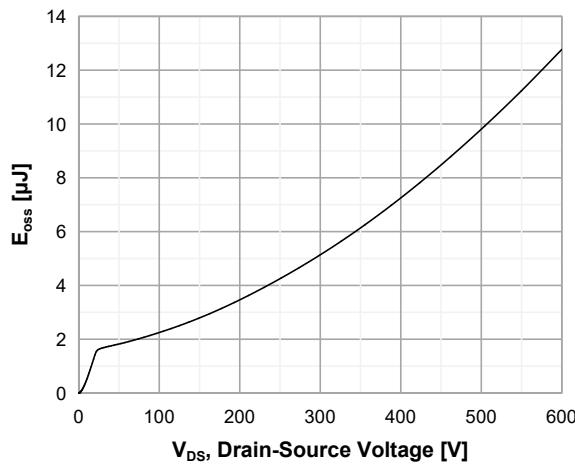


Figure 11.E_{oss} vs. Drain to Source Voltage

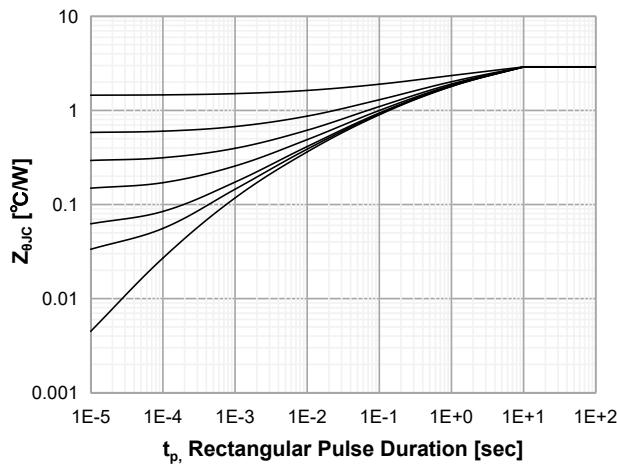
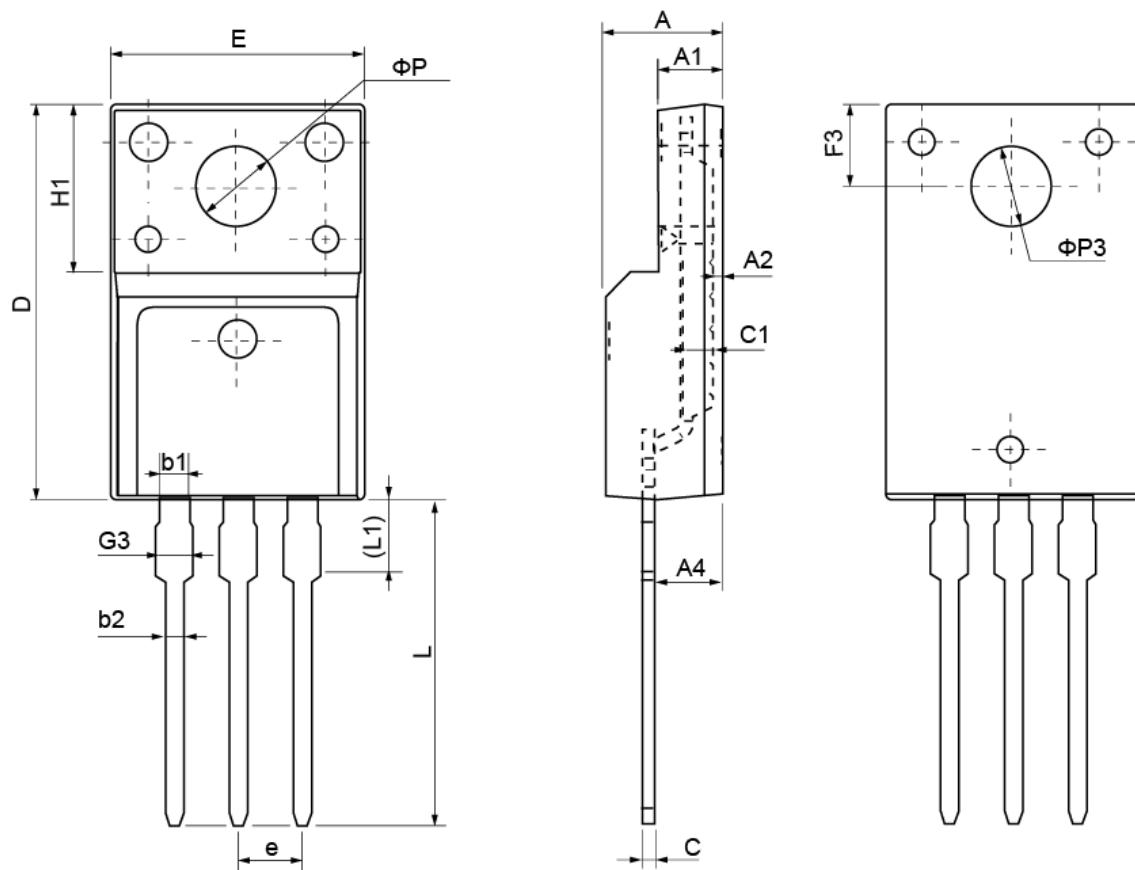


Figure 12.Transient Thermal Response Curve

650V Super Junction Power MOSFET
TO-220F Package Outline Dimensions


| Symbol | Dimensions (unit:mm) | | | Symbol | Dimensions (unit:mm) | | |
|--------|----------------------|-------|-------|--------|----------------------|-------|-------|
| | Min | Typ | Max | | Min | Typ | Max |
| A | 4.40 | 4.70 | 5.00 | H1 | 6.70 REF | | |
| A1 | 2.30 | 2.55 | 2.80 | L | 12.30 | 12.98 | 13.30 |
| A2 | 0.30 | 0.50 | 0.70 | L1 | 2.95 | 3.10 | 3.50 |
| A4 | 2.45 | 2.80 | 3.05 | φP | 3.03 | 3.20 | 3.50 |
| c | 0.30 | 0.50 | 0.70 | φP3 | 3.15 | 3.45 | 3.65 |
| c1 | 1.20 | 1.30 | 1.40 | b1 | 1.10 | 1.30 | 1.45 |
| D | 15.40 | 15.90 | 16.40 | b2 | 0.60 | 0.80 | 1.00 |
| E | 9.86 | 10.16 | 10.46 | F3 | 3.05 | 3.30 | 3.55 |
| e | 2.54 BSC | | | G3 | 1.15 | 1.35 | 1.55 |